

Description

The DFS360HF12DFC1 is a Half Bridge SiC MOSFET Power Module. It integrates high performance SiC MOSFET chips and SiC Diode designed for the applications such as Motor drives and Renewable energy.



Features

- Blocking voltage:1200V
- $R_{ds(on)} = 4.3m\Omega$
- Low thermal resistance with Si₃N₄ AMB
- 175°C maximum junction temperature
- 62mm halfbridge module

Applications

- Motor Drives
- Vehicle Fast Chargers
- Renewable energy
- UPS

Circuit diagram

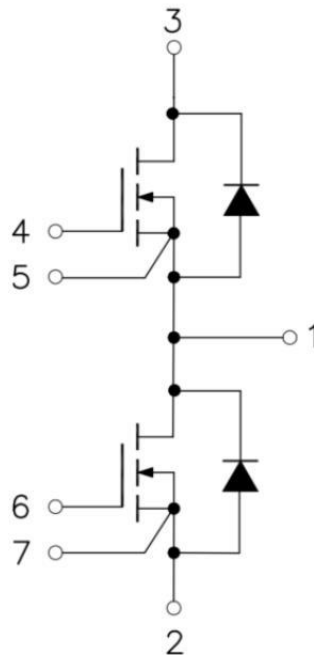


Figure 1. Out drawing & circuit diagram for DFS360HF12DFC1

Pin Configuration and Marking Information

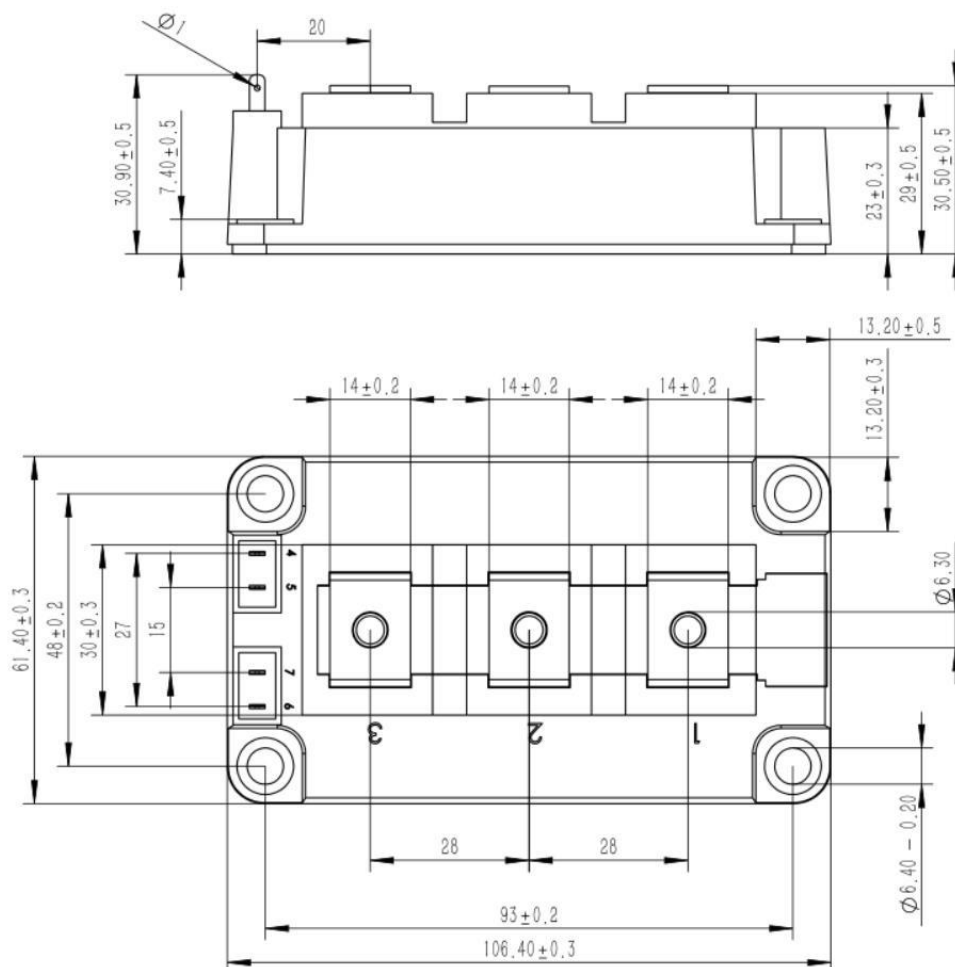


Figure 2. Pin configuration

Module

Parameter	Conditions	Value	Unit
Isolation Voltage	RMS, f=50Hz, t=1min	3.4	kV
Material of module baseplate	-	Cu	-
Creepage distance	terminal to heatsink	14.5	mm

	terminal to terminal	10	
Clearance	terminal to heatsink terminal to terminal	12.5 10	mm
CTI	-	>400	-
Module lead resistance, terminals - chip	T _c = 25°C	0.6	mΩ
Mounting torque for module mounting	M6	4 to 6	Nm
Weight	-	320	g

Preliminary datasheet _Ver.1.0 EN

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Maximum Ratings ($T_j = 25^\circ\text{C}$ unless otherwise specified)

Symbol	Parameter	Conditions	Ratings	Unit
V_{DS}	Drain-Source Voltage	G-S Short	1200	V
V_{GS}	Gate-Source Voltage	D-S Short, AC frequency $\geq 1\text{Hz}$, Note1	-10 to 22	V
I_{DS}	DC Continuous Drain Current	$T_c = 25^\circ\text{C}$, $V_{GS} = 18\text{V}$	480	A
I_{DS}	DC Continuous Drain Current	$T_c = 80^\circ\text{C}$, $V_{GS} = 18\text{V}$	360	A
I_{DSM}	Pulse Drain Current	$T_c = 25^\circ\text{C}$, Pulse width = 1ms, $V_{GS} = +18\text{V}$, Note2	800	A
I_F	Forward Current (Diode)	$T_c = 25^\circ\text{C}$, with ON signal	500	A
I_F	Forward Current (Diode)	$T_c = 80^\circ\text{C}$, with ON signal	380	A
I_{FRM}	Pulse Forward Current (Diode)	Less than 1ms, Note2	800	A
P_{tot}	Total Power Dissipation	$T_c = 25^\circ\text{C}$	1500	W
T_{jmax}	Max Junction Temperature	-	175	$^\circ\text{C}$
T_{stg}	Storage Temperature	-	-40 to 125	$^\circ\text{C}$

Note1: Recommended Operating Value, +18V/-5V, +18V/-4V, +15V/-4V

Note2: Pulse width limited by maximum junction temperature

MOSFET Electrical characteristics ($T_j = 25^\circ\text{C}$ unless otherwise specified, chip)

Symbol	Item	Condition		Value			Unit
				Min.	Typ.	Max	
V _{(BR)DSS}	Drain-Source Breakdown Voltage	V _{GS} =0V, I _D =400uA		1200	-	-	V
I _{DSS}	Zero gate voltage drain Current	V _{DS} =1200V, V _{GS} =0V		-	4	-	μA
V _{GS(th)}	Gate-source threshold Voltage	I _D =140mA, V _{DS} =V _{GS}	T _j =25°C	1.8	2.7	-	V
			T _j =175°C	-	2.05	-	V
I _{GSS}	Gate-Source Leakage Current	V _{GS} =20V, V _{DS} =0V	T _j =25°C	-	-	400	nA
R _{DS(on)}		I _D =360A V _{GS} =+15V	T _j =25°C	-	5.3	-	mΩ
			T _j =175°C	-	7.5	-	mΩ

(Chip)	Static drain-source On-state resistance	$I_D=360A$ $V_{GS}=+18V$	$T_j=25^{\circ}C$	-	4.3	-	mΩ
			$T_j=175^{\circ}C$	-	6.4	-	mΩ
$V_{DS(on)}$ (Chip)	Static drain-source On-state Voltage	$I_D=360A$ $V_{GS}=+15V$	$T_j=25^{\circ}C$	-	2.37	-	V
			$T_j=175^{\circ}C$	-	3.62	-	V
		$I_D=360A$ $V_{GS}=+18V$	$T_j=25^{\circ}C$	-	1.55	-	V
			$T_j=175^{\circ}C$	-	2.30	-	V
C_{iss}	Input Capacitance	$V_D=800V, V_{GS}=0V, f=100kHz,$ $V_{AC}=25mV$		-	23260	-	pF
C_{oss}	Output Capacitance			-	708	-	pF
C_{rss}	Reverse transfer Capacitance			-	57	-	pF
R_{Gint}	Internal gate resistor	$f=100kHz, V_{AC}=25mV$		-	1.6	-	Ω
Q_g	Total gate charge	$V_{DD}=800V, I_D=240A, V_{GS}=+18/-4V$		-	780	-	nC
$t_{d(on)}$	Turn-on delay time		$T_j=25^{\circ}C$	-	83	-	ns

			$T_j=150^{\circ}\text{C}$	-	70	-	
t_r	Rise time	$V_{DD}=600\text{V}$ $I_D=360\text{A}$ $V_{GS}=+18/-4\text{V}$ $R_{gon}/R_{goff}=7.5\Omega/7.5\Omega$ $C_{GS}=10\text{nF}$ Inductive load switching operation	$T_j=25^{\circ}\text{C}$	-	50	-	ns
			$T_j=150^{\circ}\text{C}$	-	41	-	
$t_{d(off)}$	Turn-off delay time		$T_j=25^{\circ}\text{C}$	-	170	-	ns
			$T_j=150^{\circ}\text{C}$	-	198	-	
t_f	Fall time		$T_j=25^{\circ}\text{C}$	-	55	-	ns
			$T_j=150^{\circ}\text{C}$	-	58	-	
E_{on}	Turn-on power dissipation		$T_j=25^{\circ}\text{C}$	-	6.5	-	mJ
			$T_j=150^{\circ}\text{C}$	-	4.4	-	
E_{off}	Turn-off power dissipation		$T_j=25^{\circ}\text{C}$	-	8.2	-	mJ
			$T_j=150^{\circ}\text{C}$	-	8.7	-	
$R_{th(j-c)}$	FET Thermal Resistance	Junction to Case		-	0.1	-	$^{\circ}\text{C}/\text{W}$

SiC SBD Electrical characteristics ($T_j=25^{\circ}\text{C}$ unless otherwise specified, chip)

Symbol	Item	Condition		Value			Unit
				Min.	Typ.	Max	
V _F	Diode Forward Voltage	I _F =360A, V _{GS} =0V	T _j =25°C	-	2.10	-	V
			T _j =150°C	-	3.23	-	
t _{rr}	Diode Reverse Recovery Time	(Switch side) V _{DD} =600V, I _D =360A V _{GS} =+18V/-4V	T _j =25°C		31		ns
			T _j =150°C		32		
I _{RM}	Peak reverse recovery Current	R _{gon} /R _{goff} =7.5Ω/7.5Ω C _{GS} =10nF	T _j =25°C	-	140	-	A
			T _j =150°C	-	166	-	
Q _{rr}	Recovered charge	(FRD side) V _{RR} =600V, I _F =360A V _{GS} =+18V/-4V	T _j =25°C	-	2.6	-	uC
			T _j =150°C	-	3.2	-	
E _{rr}	Reverse recovered energy	Inductive load switching operation	T _j =25°C	-	0.8	-	mJ
			T _j =150°C	-	1.4	-	
R _{th(j-c)}	Thermal Resistance, Junction to Case (Diode)			-	0.095	-	°C/W

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Test Conditions

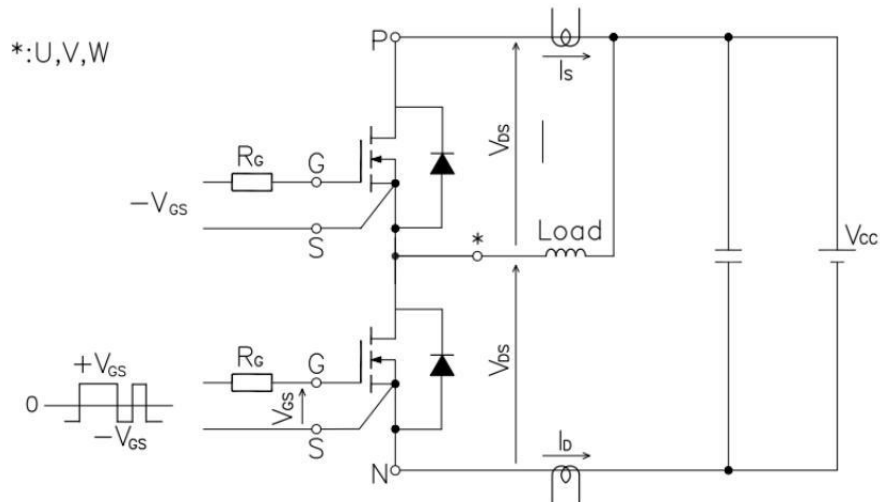


Figure 3. Switching time measure circuit

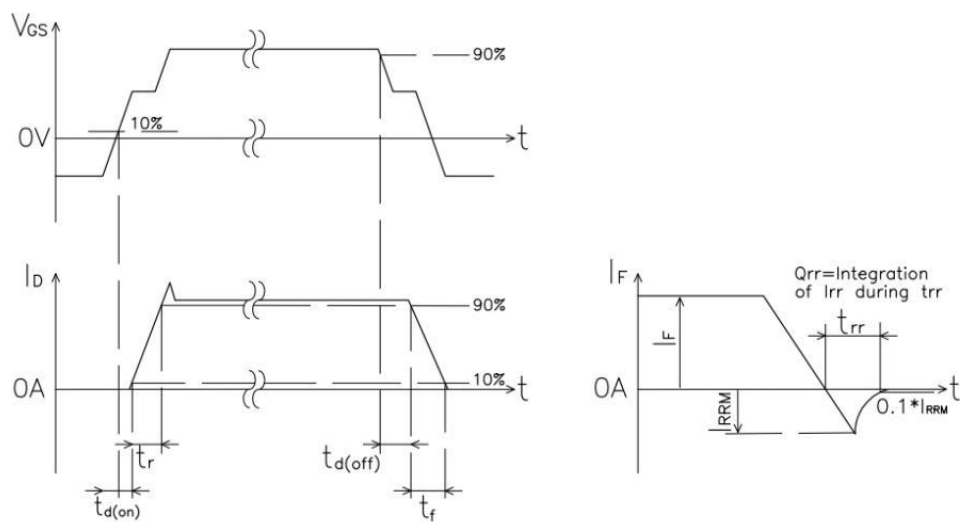


Figure 4. Switching time definition

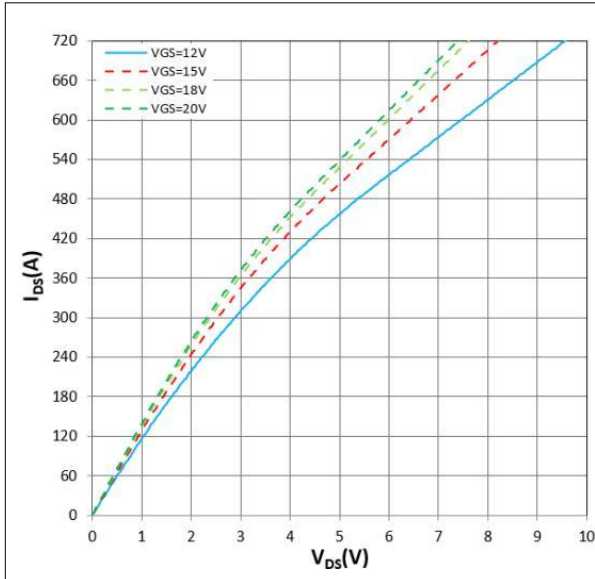


Figure 5. I_{DS} vs V_{DS}
 $T_j = 25^\circ\text{C}$

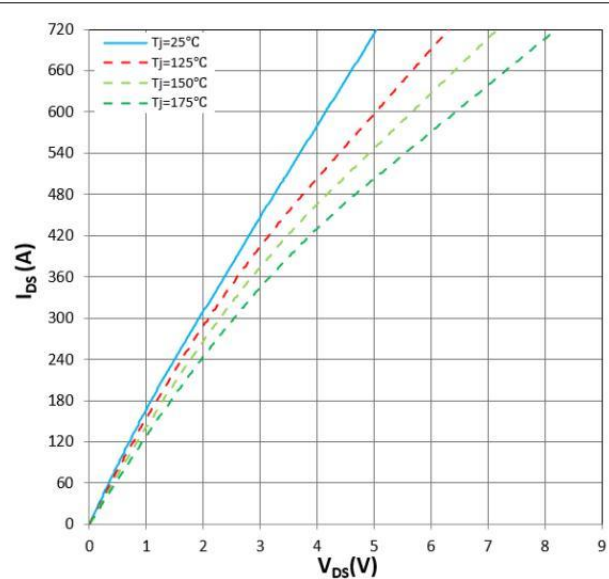


Figure 6. I_{DS} vs V_{DS}
 $V_{GS} = +15\text{V}$

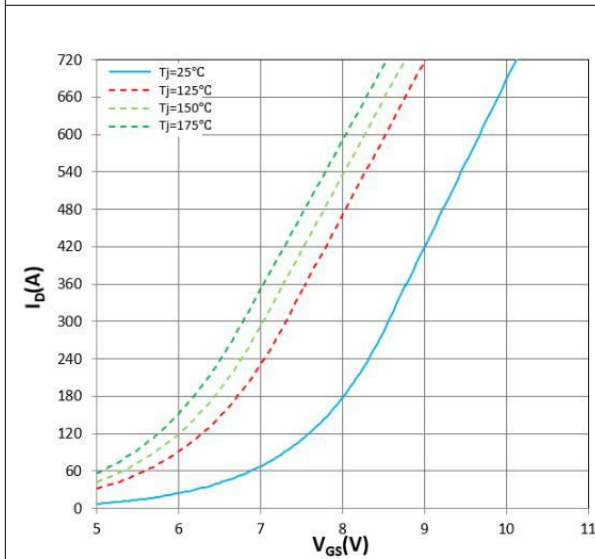


Figure 7. I_D vs V_{GS}
 $V_{DS} = 20\text{V}$

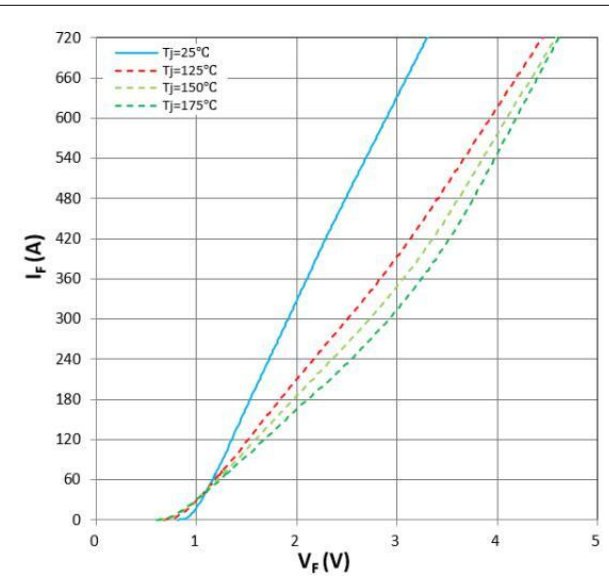


Figure 8. I_F vs V_F
 $V_{GS} = 0\text{V}$

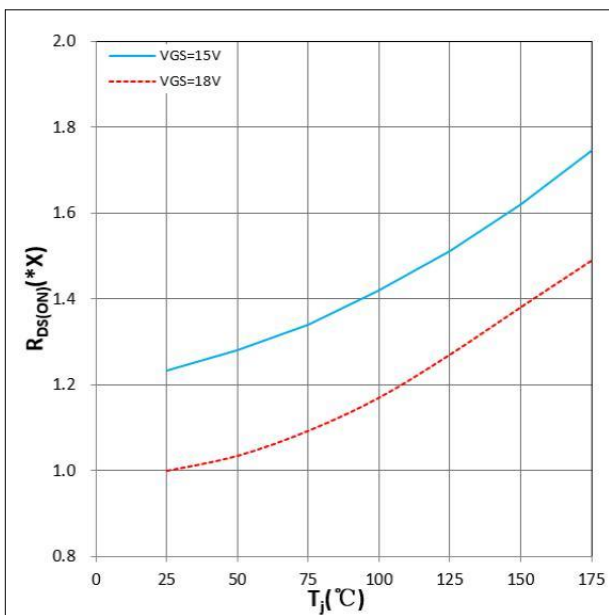


Figure 9. $R_{DS(ON)}$ vs T_J

$V_{GS} = +15V/+18V$, $I_D = 360A$, $1.0X = 4.3m\Omega$

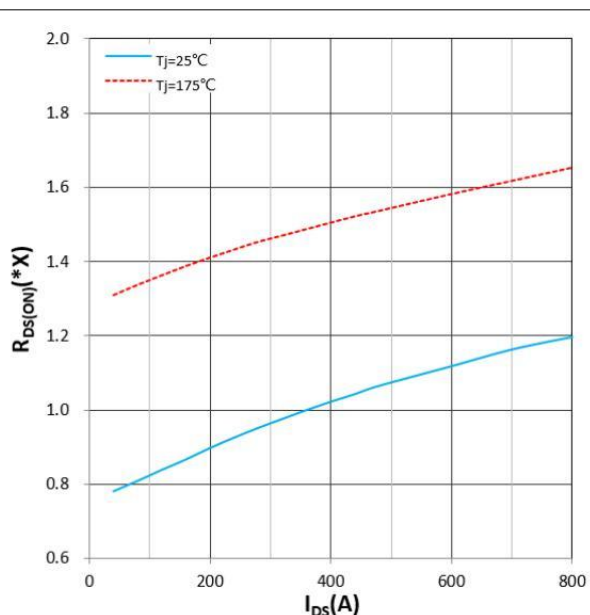


Figure 10. $R_{DS(ON)}$ vs I_{DS}

$V_{GS} = +18V$, $1.0X = 4.3m\Omega$

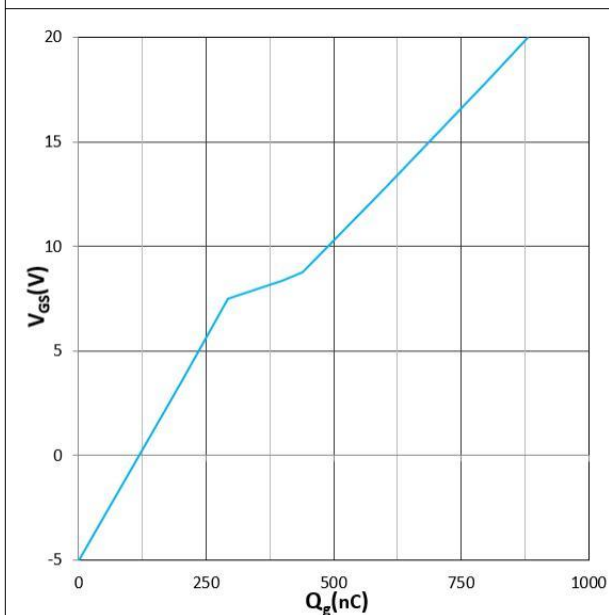


Figure 11. V_{GS} vs Q_g

$V_{DS} = 800V$, $I_D = 240A$, $T_J = 25^\circ C$

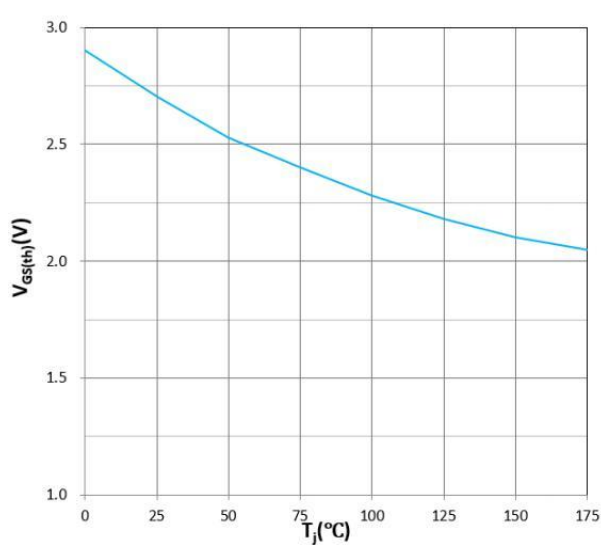


Figure 12. $V_{GS(TH)}$ vs T_J

$V_{GS} = V_{DS}$, $I_D = 140mA$

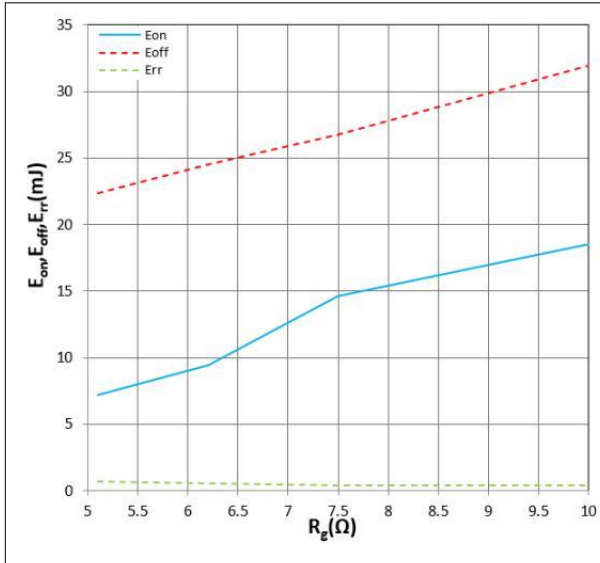


Figure 13. E_{on} , E_{off} , E_{rr} vs R_g
 $T_j=25^{\circ}\text{C}$, $V_{DD}=600\text{V}$, $V_{GS}=+18\text{V}/-4\text{V}$, $I_D=360\text{A}$
 $C_{GS}=10\text{nF}$, Inductive Load

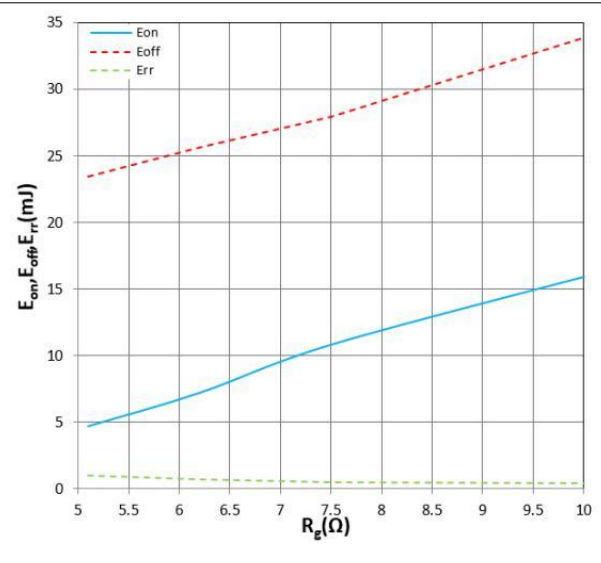


Figure 14. E_{on} , E_{off} , E_{rr} vs R_g
 $T_j=150^{\circ}\text{C}$, $V_{DD}=600\text{V}$, $V_{GS}=+18\text{V}/-4\text{V}$, $I_D=360\text{A}$
 $C_{GS}=10\text{nF}$, Inductive Load

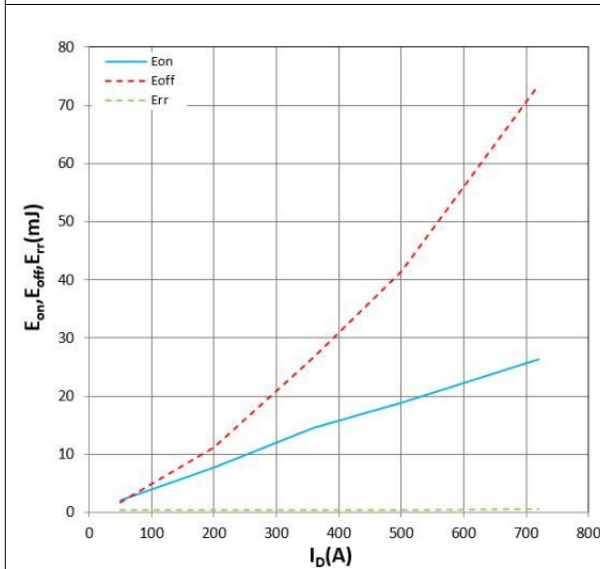


Figure 15. E_{on} , E_{off} , E_{rr} vs I_{DS}
 $T_j=25^{\circ}\text{C}$, $V_{DD}=600\text{V}$, $V_{GS}=+18\text{V}/-4\text{V}$
 $R_{gon}/R_{goff}=7.5\Omega/7.5\Omega$, $C_{GS}=10\text{nF}$, Inductive Load

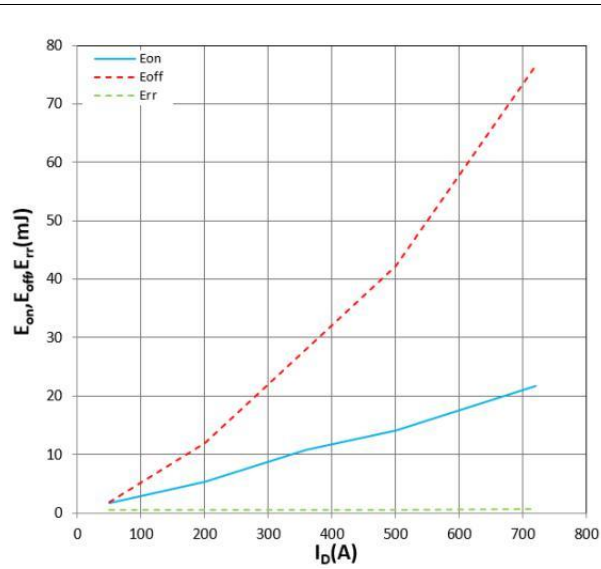


Figure 16. E_{on} , E_{off} , E_{rr} vs I_{DS}
 $T_j=150^{\circ}\text{C}$, $V_{DD}=600\text{V}$, $V_{GS}=+18\text{V}/-4\text{V}$
 $R_{gon}/R_{goff}=7.5\Omega/7.5\Omega$, $C_{GS}=10\text{nF}$, Inductive Load

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